

# COS/MOS INTEGRATED CIRCUIT

S G S-THOMSON 07C D 7929237 0014692 0



41C 08705 DT-4607-07

## DJAL J-K MASTER-SLAVE FLIP-FLOP

- SET-RESET CAPABILITY
- STATIC FLIP-FLOP OPERATION - RETAINS STATE INDEFINITELY WITH CLOCK LEVEL EITHER "HIGH" OR "LOW"
- MEDIUM SPEED OPERATION -16 MHz (TYP. CLOCK TOGGLE RATE AT 10V)
- STANDARDIZED SYMMETRICAL OUTPUT CHARACTERISTICS
- QUIESCENT CURRENT SPECIFIED TO 20V FOR HCC DEVICE
- INPUT CURRENT OF 100 nA AT 18V AND 25°C FOR HCC DEVICE
- 100% TESTED FOR QUIESCENT CURRENT
- MEETS ALL REQUIREMENTS OF JEDEC TENTATIVE STANDARD NO. 13A, "STANDARD SPECIFICATIONS FOR DESCRIPTION OF "B" SERIES CMOS DEVICES"

The **HCC 4027B** (extended temperature range) and **HCF 4027B** (intermediate temperature range) are monolithic integrated circuit, available in 16-lead dual in-line plastic or ceramic package, ceramic flat package and plastic micropackage.

The **HCC/HCF 4027B** is a single monolithic chip integrated circuit containing two identical complementary-symmetry J-K master-slave flip-flops. Each flip-flop has provisions for individual J, K, Set, Reset, and Clock input signals, Buffered Q and  $\bar{Q}$  signals are provided as outputs. This input-output arrangement provides for compatible operation with the **HCC/HCF 4013B** dual D-type flip-flop.

The **HCC/HCF 4027B** is useful in performing control, register, and toggle functions. Logic levels present at the J and K inputs along with internal self-steering control the state of each flip-flop; changes in the flip-flop state are synchronous with the positive-going transition of the clock pulse. Set and reset functions are independent of the clock and are initiated when a high level signal is present at either the Set or Reset input.

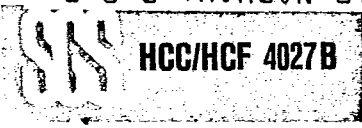
## ABSOLUTE MAXIMUM RATINGS

$V_{DD}^*$	Supply voltage: <b>HCC</b> types <b>HCF</b> types	-0.5 to 20 -0.5 to 18	V V
$V_I$	Input voltage	-0.5 to $V_{DD} + 0.5$	V
$I_I$	DC input current (any one input)	$\pm 10$	mA
$P_{tot}$	Total power dissipation (per package) Dissipation per output transistor for $T_{op}$ = full package-temperature range	200 100	mW mW
$T_{op}$	Operating temperature: <b>HCC</b> types <b>HCF</b> types	-55 to 125 -40 to 85	°C °C
$T_{stg}$	Storage temperature	-65 to 150	°C

\* All voltage values are referred to  $V_{SS}$  pin voltage

## ORDERING NUMBERS:

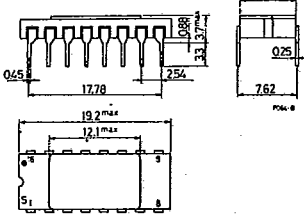
HCC 4027 BD for dual in-line ceramic package  
HCC 4027 BF for dual in-line ceramic package, frit seal  
HCC 4027 BK for ceramic flat package  
HCF 4027 BE for dual in-line plastic package  
HCF 4027 BF for dual in-line ceramic package, frit seal  
HCF 4027 BM for plastic micropackage



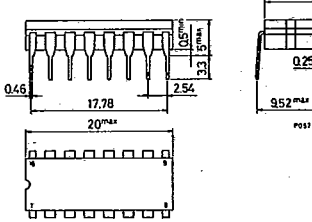
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**MECHANICAL DATA** (dimensions in mm)

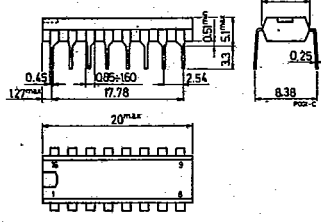
Dual in-line ceramic package for HCC 4027 BD



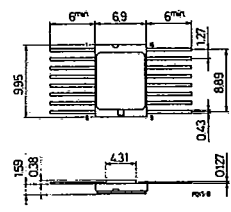
Dual in-line ceramic package for HCC/HCF 4027 BF



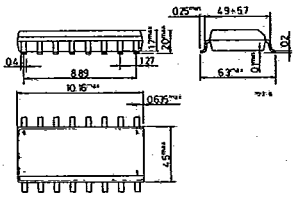
Dual in-line plastic package for HCF 4027 BE



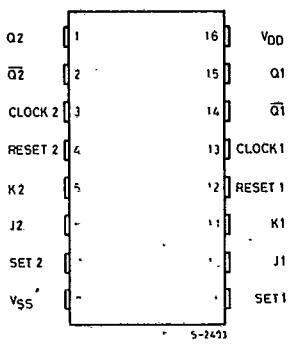
Ceramic flat package for HCC 4027 BK



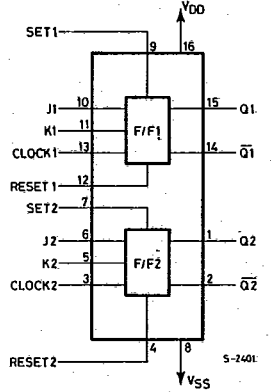
Plastic micropackage for HCF 4027 BM



**CONNECTION DIAGRAM**



**FUNCTIONAL DIAGRAM**



**RECOMMENDED OPERATING CONDITIONS**

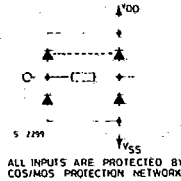
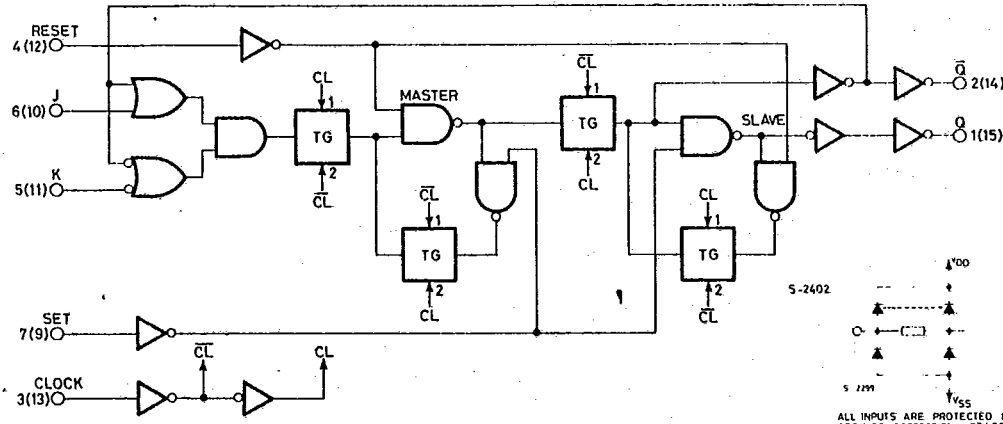
$V_{DD}$	Supply voltage: HCC types HCF types	3 to 18 V 3 to 15 V	V
$V_I$	Input voltage	0 to $V_{DD}$	V
$T_{op}$	Operating temperature: HCC types HCF types	-55 to 125 °C -40 to 85 °C	°C



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**LOGIC DIAGRAM AND TRUTH TABLE**

One of two identical J-K flip-flops

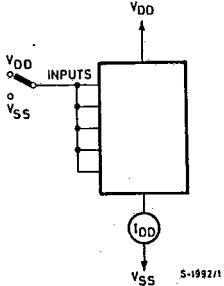


PRESENT STATE					CL <sup>Δ</sup>	NEXT STATE	
J	K	S	R	Q		Q	Q̄
1	X	0	0	0		1	0
X	0	0	0	1		1	0
0	X	0	0	0		0	1
X	1	0	0	1		0	1
X	X	0	0	X			← NO CHANGE
X	X	1	0	X	X	1	0
X	X	0	1	X	X	0	1
X	X	1	1	X	X	1	1

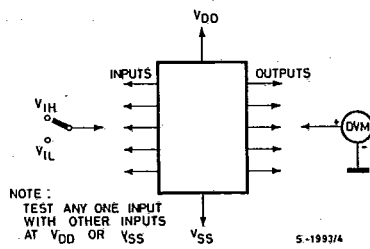
LOGIC 1 = HIGH LEVEL  
 LOGIC 0 = LOW LEVEL  
 Δ - LEVEL CHANGE  
 X - DON'T CARE

**TEST CIRCUITS**

Quiescent device current

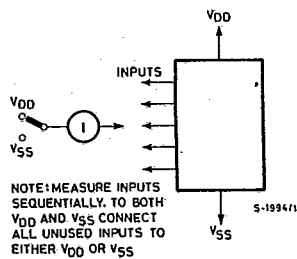


Input voltage



NOTE: TEST ANY ONE INPUT WITH OTHER INPUTS AT VDD OR VSS

Input leakage current



NOTE: MEASURE INPUTS SEQUENTIALLY TO BOTH VDD AND VSS CONNECT ALL UNUSED INPUTS TO EITHER VDD OR VSS

HCC/HCF 4027B

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## STATIC ELECTRICAL CHARACTERISTICS (over recommended operating conditions)

Parameter		Test conditions				Values						Unit		
		V <sub>I</sub> (V)	V <sub>O</sub> (V)	I <sub>OL</sub>   ( $\mu$ A)	V <sub>DD</sub> (V)	T <sub>Low</sub> *		25°C			T <sub>High</sub> *			
						Min.	Max.	Min.	Typ.	Max.	Min.		Max.	
I <sub>L</sub>	Quiescent current	HCC types	0/5			5		1		0.02	1		30	$\mu$ A
			0/10			10		2		0.02	2		60	
			0/15			15		4		0.02	4		120	
		0/20			20		20		0.04	20		600		
		HCF types	0/5			5		4		0.02	4		30	
			0/10			10		8		0.02	8		60	
0/15				15		16		0.02	16		120			
V <sub>OH</sub>	Output high voltage	0/5		< 1	5	4.95		4.95			4.95		V	
		0/10		< 1	10	9.95		9.95			9.95			
		0/15		< 1	15	14.95		14.95			14.95			
V <sub>OL</sub>	Output low voltage	5/0		< 1	5		0.05			0.05		0.05	V	
		10/0		< 1	10		0.05			0.05		0.05		
		15/0		< 1	15		0.05			0.05		0.05		
V <sub>IH</sub>	Input high voltage		0.5/4.5	< 1	5	3.5		3.5			3.5		V	
			1/9	< 1	10	7		7			7			
			1.5/13.5	< 1	15	11		11			11			
V <sub>IL</sub>	Input low voltage		4.5/0.5	< 1	5		1.5			1.5		1.5	V	
			9/1	< 1	10		3			3		3		
			13.5/1.5	< 1	15		4			4		4		
I <sub>OH</sub>	Output drive current	HCC types	0/5	2.5		5	-2		-1.6	-3.2		-1.15	mA	
			0/5	4.6		5	-0.64		-0.51	-1		-0.36		
			0/10	9.5		10	-1.6		-1.3	-2.6		-0.9		
		0/15	13.5		15	-4.2		-3.4	-6.8		-2.4			
		HCF types	0/5	2.5		5	-1.53		-1.36	-3.2		-1.1		
			0/5	4.6		5	-0.52		-0.44	-1		-0.36		
0/10	9.5			10	-1.3		-1.1	-2.6		-0.9				
0/15	13.5		15	-3.6		-3.0	-6.8		-2.4					
I <sub>OL</sub>	Output sink current	HCC types	0/5	0.4		5	0.64		0.51	1		0.36	mA	
			0/10	0.5		10	1.6		1.3	2.6		0.9		
			0/15	1.5		15	4.2		3.4	6.8		2.4		
		HCF types	0/5	0.4		5	0.52		0.44	1		0.36		
			0/10	0.5		10	1.3		1.1	2.6		0.9		
			0/15	1.5		15	3.6		3.0	6.8		2.4		
I <sub>IH</sub> , I <sub>IL</sub>	Input leakage current	HCC types	0/18	Any input	18		$\pm 0.1$		$\pm 10^{-5}$	$\pm 0.1$		$\pm 1$	$\mu$ A	
		HCF types	0/15		15		$\pm 0.3$		$\pm 10^{-5}$	$\pm 0.3$		$\pm 1$		
C <sub>I</sub>	Input capacitance		.Any input					5	7.5			pF		

\* T<sub>Low</sub> = -55°C for HCC device; -40°C for HCF device.\* T<sub>High</sub> = +125°C for HCC device; +85°C for HCF device.The Noise Margin for both "1" and "0" level is: 1V min. with V<sub>DD</sub> = 5V  
2V min. with V<sub>DD</sub> = 10V  
2.5V min. with V<sub>DD</sub> = 15V



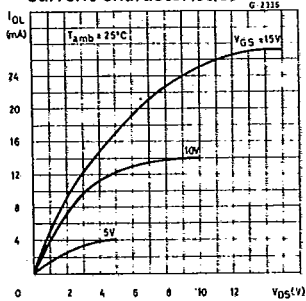
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**DYNAMIC ELECTRICAL CHARACTERISTICS** ( $T_{amb} = 25^{\circ}C$ ,  $C_L = 50$  pF,  $R_L = 200$  K $\Omega$ , typical temperature coefficient for all  $V_{DD} = 0.3\%/^{\circ}C$  values, all input rise and fall time = 20 ns)

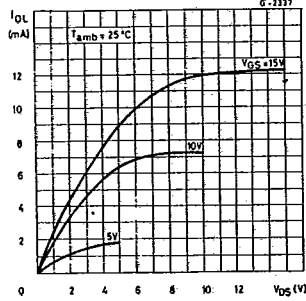
Parameter			Test conditions	Values			Unit	
				$V_{DD}(V)$	Min.	Typ.		Max.
$t_{PLH}$ , $t_{PHL}$	Propagation delay time	Clock to Q or $\bar{Q}$ outputs	5		150	300	ns	
			10		65	130		
			15		45	90		
$t_{PLH}$	Propagation delay time	Set to Q or Reset to $\bar{Q}$	5		150	300		
			10		65	130		
			15		45	90		
$t_{PHL}$	Propagation delay time	Set to $\bar{Q}$ or Reset to Q	5		200	400		
			10		85	170		
			15		60	120		
$t_{THL}$ , $t_{TLH}$	Transition time		5		100	200	ns	
			10		50	100		
			15		40	80		
$t_w$	Pulse width	Clock	5	140	70	ns		
			10	60	30			
			15	40	20			
$t_w$	Pulse width	Set or Reset	5	180	90			
			10	80	40			
			15	50	25			
$t_r$ , $t_f$	Clock input rise or fall time		5				15	$\mu s$
			10				4	
			15				1	
$t_{setup}$	Setup time	Data	5	200	100	ns		
			10	75	35			
			15	50	25			
$f_{max}$	Maximum clock input frequency*	Toggle Mode	5	3.5	7	MHz		
			10	8	16			
			15	12	24			

\* Input  $t_r$ ,  $t_f = 5$  ns.

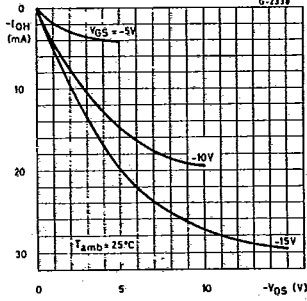
Typical output low (sink) current characteristics



Minimum output low (sink) current characteristics



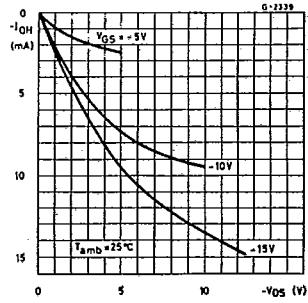
Typical output high (source) current characteristics



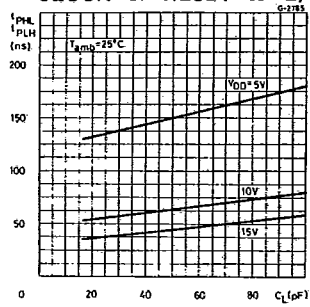


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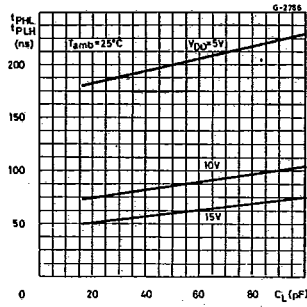
Minimum output high (source) current characteristics



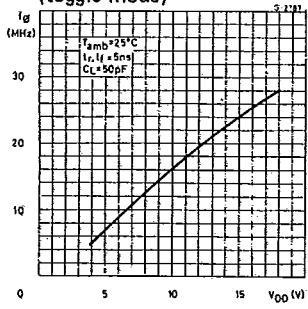
Typical propagation delay time vs. load capacitance (CLOCK or SET to Q, CLOCK or RESET to Q)



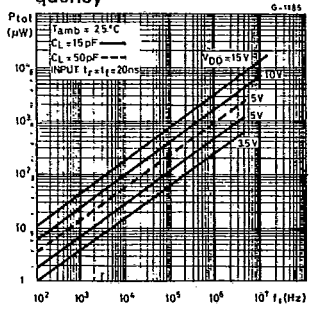
Typical propagation delay time vs. load capacitance (SET to Q or RESET to Q)

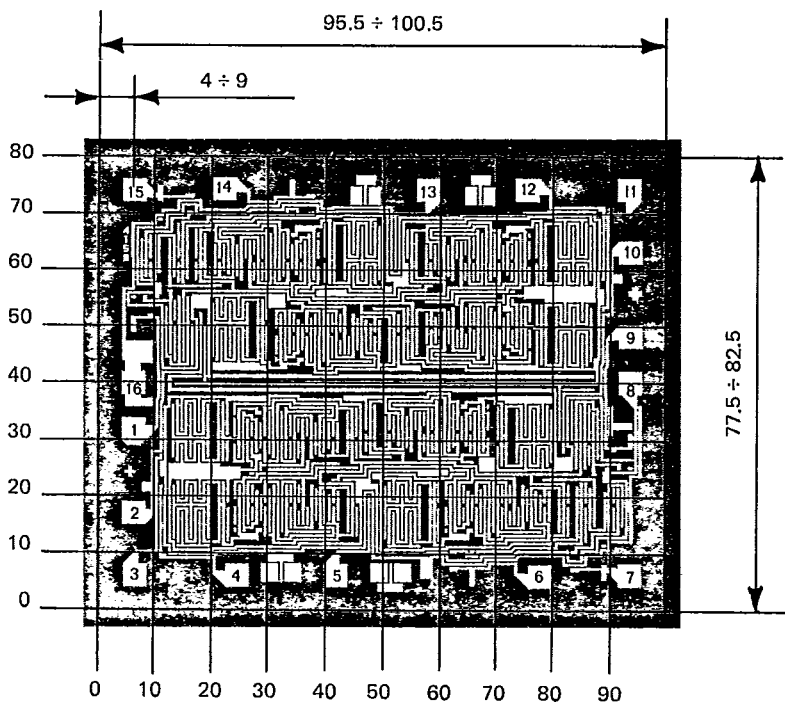


Typical maximum clock frequency vs. supply voltage (toggle mode)

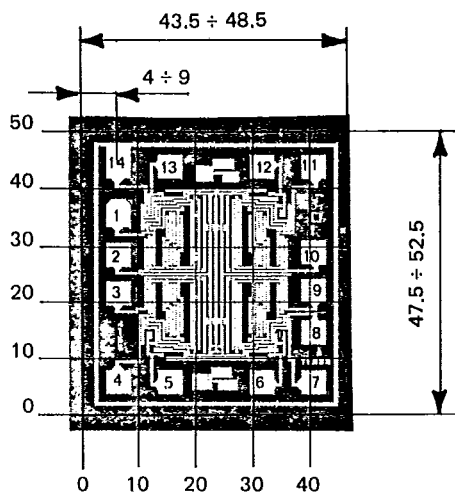


Typical dynamic power dissipation/per device vs. frequency





4015B



4016B